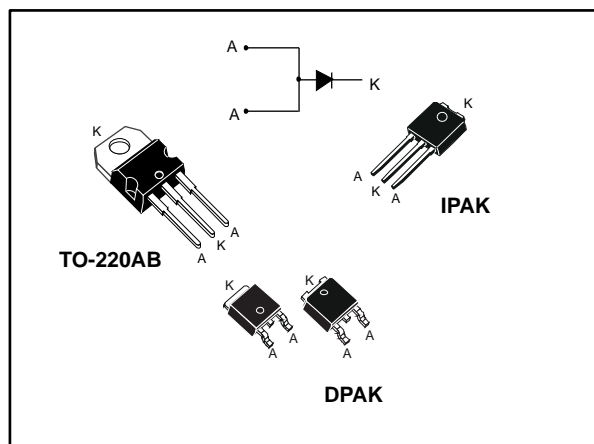


100 V field-effect rectifier diode

Datasheet - production data



Description

The device is based on a proprietary technology that achieves the best in class V_F/I_R trade-off for a given silicon surface. This 100 V rectifier has been optimized for use in confined casing applications where both efficiency and thermal performance matter. With a lower dependency of leakage current (I_R) and forward voltage (V_F) in function of temperature, the thermal runaway risk is reduced. Therefore, it can advantageously replace 100 V Schottky diodes.

Table 1: Device summary

Symbol	Value
$I_{F(AV)}$	30 A
V_{RRM}	100 V
V_F (max.)	0.405 V
I_R (max.)	130 μ A
T_j (max.)	175 °C

Features

- ST advanced rectifier process
- Stable leakage current over reverse voltage
- Reduced leakage current
- Low forward voltage drop
- High frequency operation
- ECOPACK[®]2 compliant component

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified, with anode terminals short circuited)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		100	V
I _{F(RMS)}	Forward rms current		45	A
I _{F(AV)}	Average forward current $\delta = 0.5$, square wave	T _C = 145 °C	30	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal, DPAK/IPAK	150	A
		t _p = 10 ms sinusoidal, TO-220AB	250	
T _{stg}	Storage temperature range		-65 to +175	°C
T _j	Maximum operating junction temperature ⁽¹⁾		+175	°C

Notes:

⁽¹⁾(dP_{tot}/dT_j) < (1/R_{th(j-a)}) condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal resistance parameters

Symbol	Parameter	Value	Unit
R _{th(j-c)}	Junction to case	0.9	°C/W

Table 4: Static electrical characteristics with anode terminals short circuited

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
		T _j	V _R				
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-		130	μA
		T _j = 125 °C		-	8	16	mA
		T _j = 125 °C	V _R = 70 V	-	4	7	
V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _F = 3 A	-	0.390	0.440	V
		T _j = 125 °C		-	0.350	0.405	
		T _j = 25 °C	I _F = 5 A	-	0.440	0.495	
		T _j = 125 °C		-	0.415	0.470	
		T _j = 25 °C	I _F = 10 A	-	0.550	0.620	
		T _j = 125 °C		-	0.530	0.585	
T _j = 125 °C	I _F = 30 A	-	0.680	0.745			

Notes:

⁽¹⁾Pulse test: t_p = 5 ms, $\delta < 2\%$

⁽²⁾Pulse test: t_p = 380 μs, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.424 \times I_{F(AV)} + 0.0133 I_{F(RMS)}^2$$

1.1 Characteristics (curves)

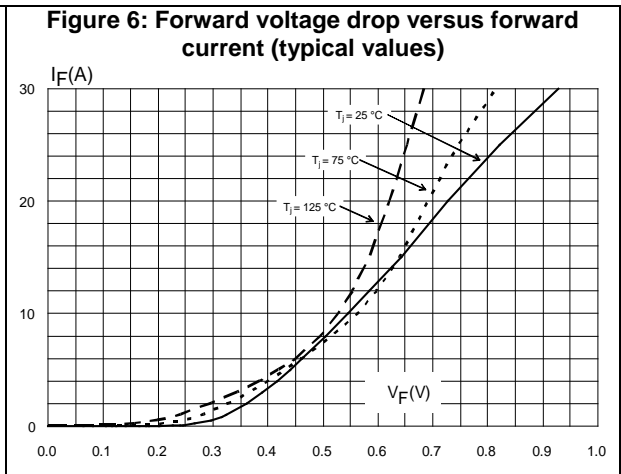
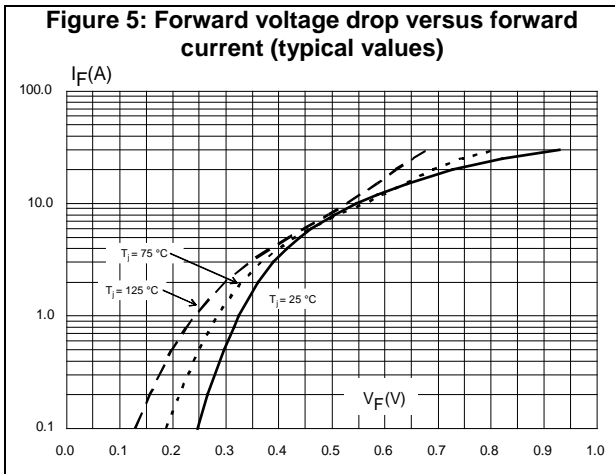
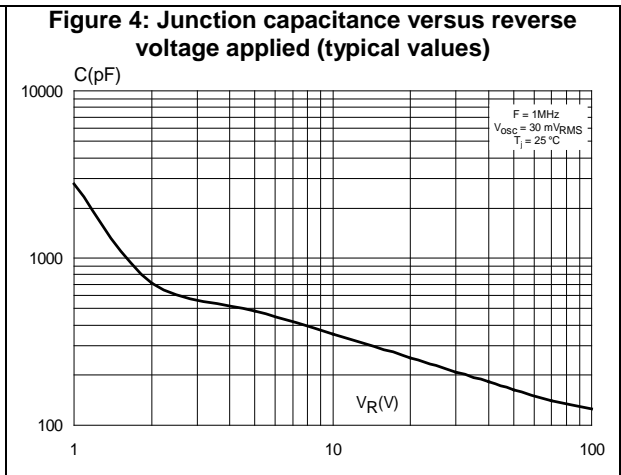
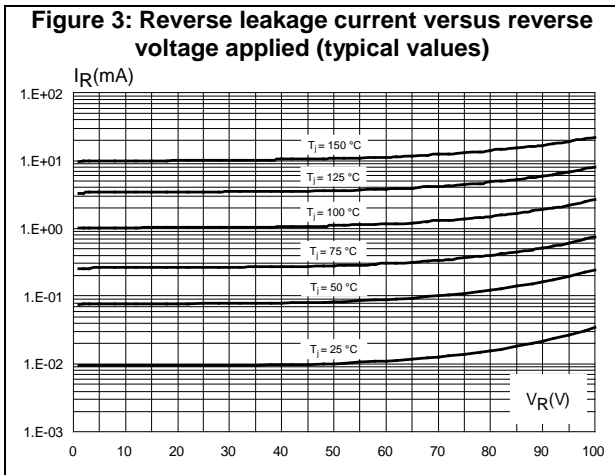
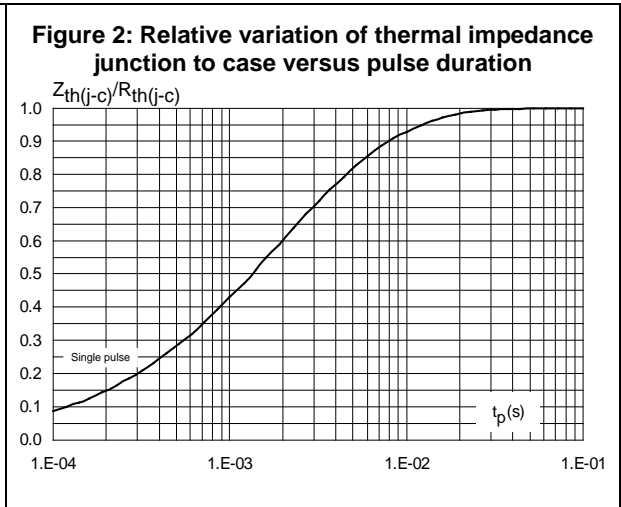
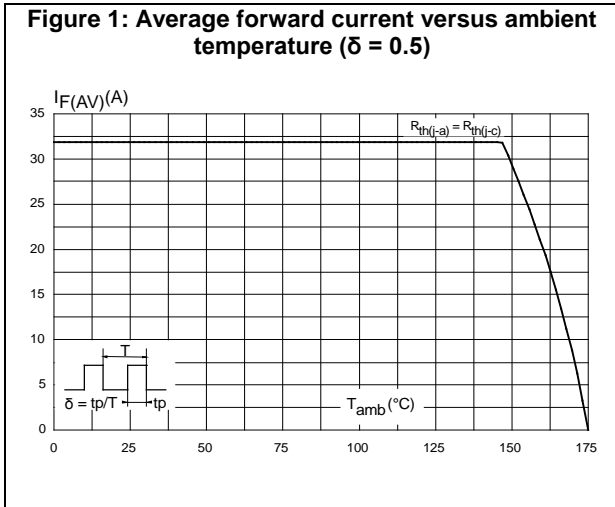
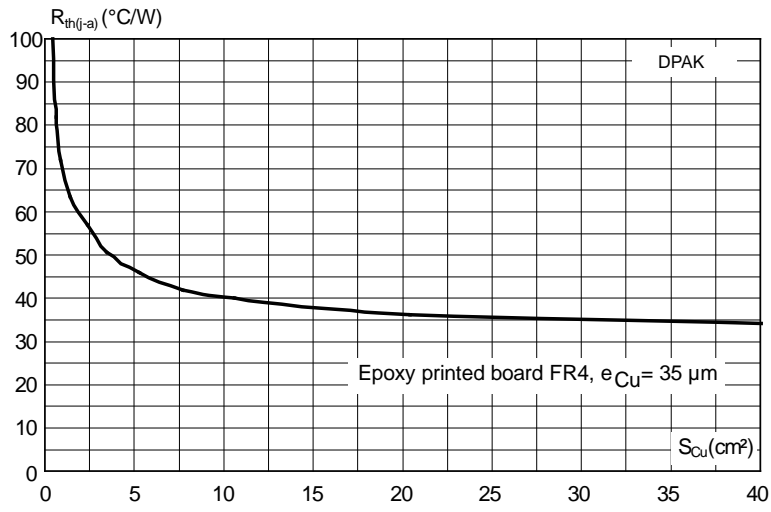


Figure 7: Thermal resistance junction to ambient versus copper surface under tab for DPAK (typical values)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL94,V0
- Recommended torque value: 0.55 N·m (for TO-220AB)
- Maximum torque value: 0.6 N·m (for TO-220AB)

2.1 TO-220AB package information

Figure 8: TO-220AB package outline

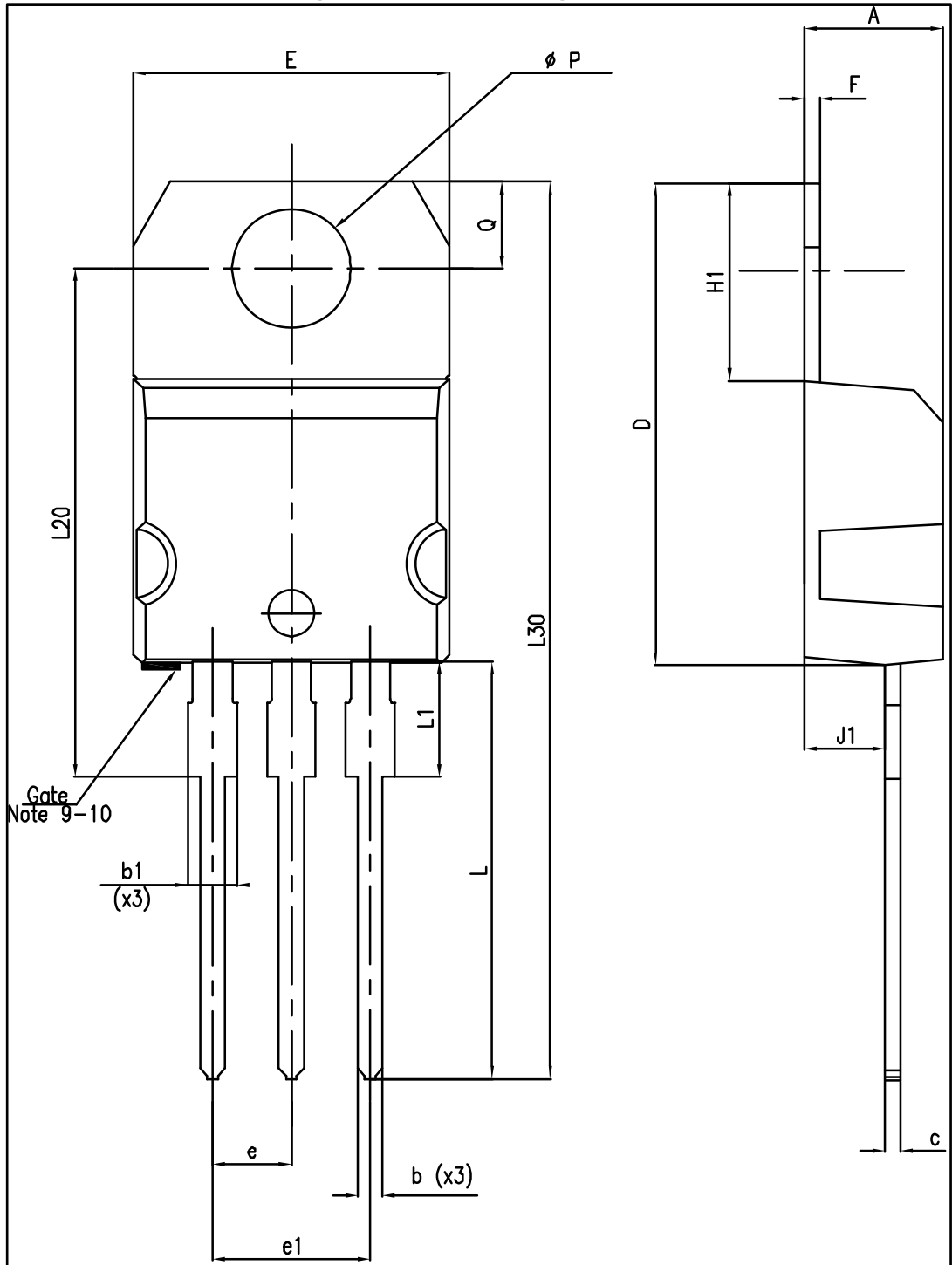
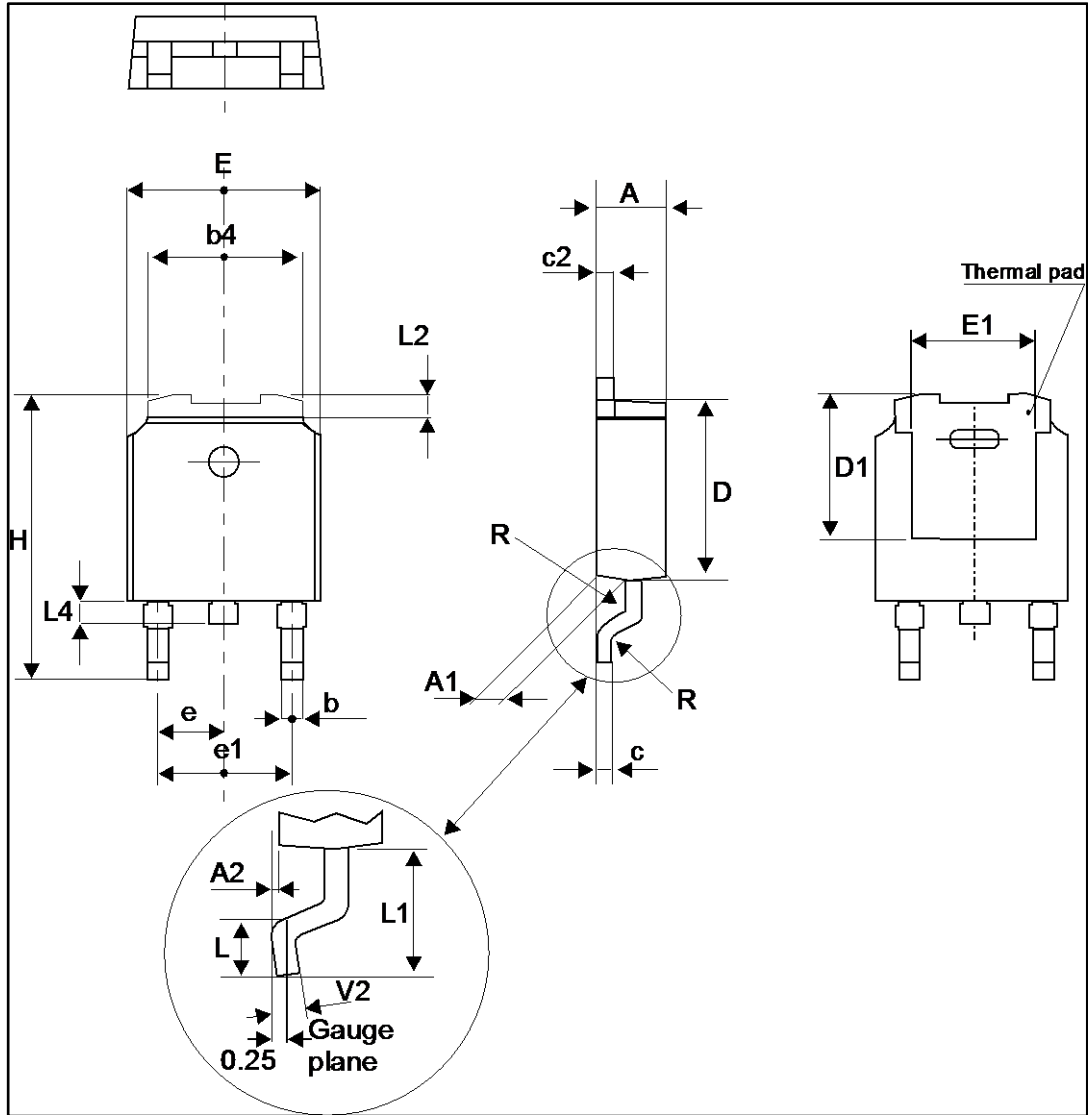


Table 5: TO-220AB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.045	0.067
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	0.51	0.60	0.020	0.024
J1	2.40	2.72	0.094	0.107
H1	6.20	6.60	0.244	0.256
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138	
Ø P	3.75	3.85	0.148	0.156
Q	2.65	2.95	0.104	0.116

2.2 DPAK package information

Figure 9: DPAK package outline

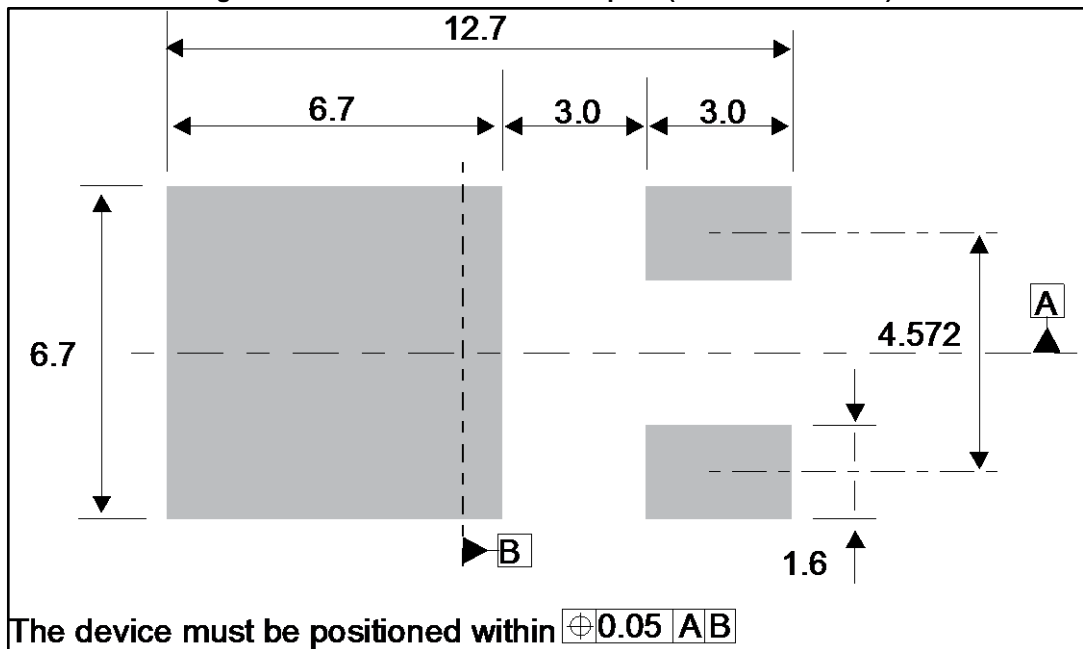


This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 6: DPAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.18	2.40	0.085	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
b	0.64	0.90	0.025	0.035
b4	4.95	5.46	0.194	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.60	0.018	0.023
D	5.97	6.22	0.235	0.244
D1	4.95	5.60	0.194	0.220
E	6.35	6.73	0.250	0.265
E1	4.32	5.50	0.170	0.216
e	2.286 typ.		0.090 typ.	
e1	4.40	4.70	0.173	0.185
H	9.35	10.40	0.368	0.409
L	1.0	1.78	0.039	0.070
L2		1.27		0.050
L4	0.60	1.02	0.023	0.040
V2	-8°	+8°	-8°	+8°

Figure 10: DPAK recommended footprint (dimensions in mm)



2.3 IPAK package information

Figure 11: IPAK package outline

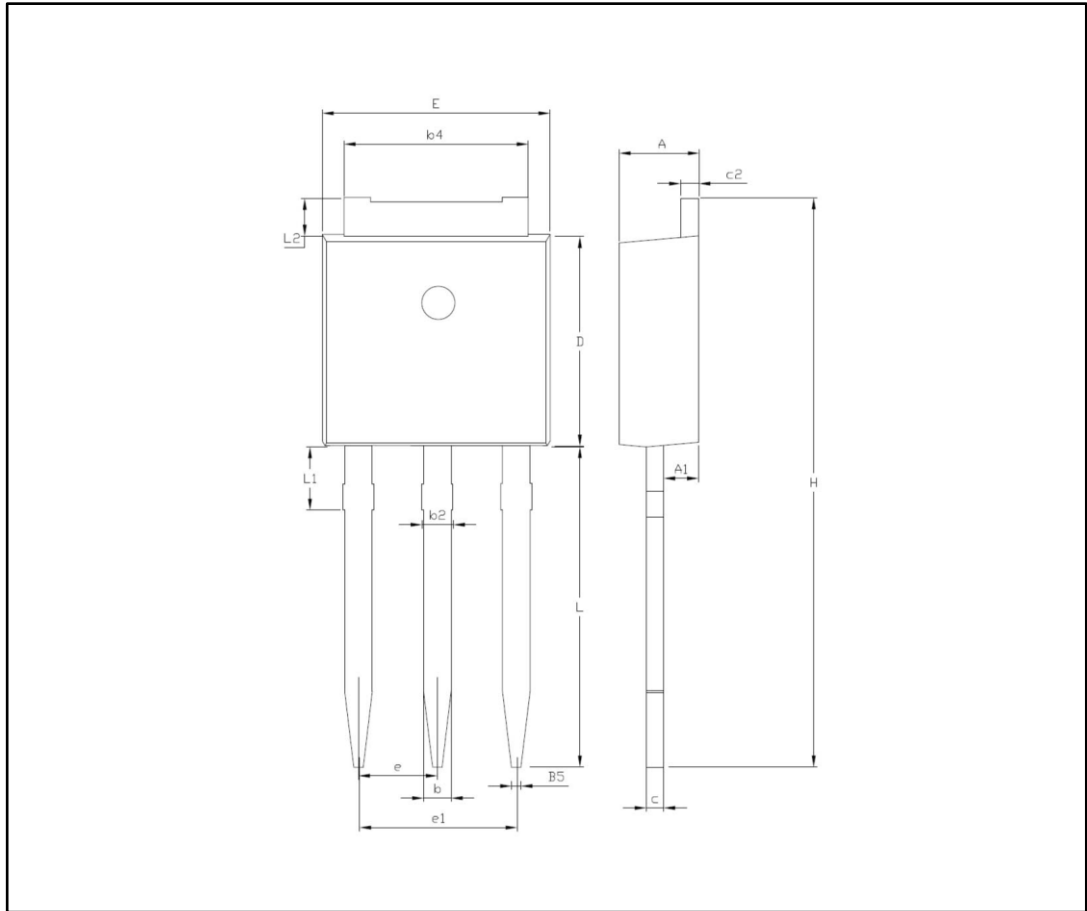


Table 7: IPAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.087	0.094
A1	0.90	1.10	0.035	0.043
b	0.64	0.90	0.025	0.035
b2		0.95		0.037
b4	5.20	5.43	0.205	0.214
B5	0.30 typ.		0.012 typ.	
c	0.45	0.60	0.018	0.024
c2	0.46	0.60	0.018	0.024
D	6.00	6.20	0.236	0.244
E	6.40	6.65	0.252	0.261
e	2.28 typ.		typ.0.090	
e1	4.40	4.60	0.173	0.181
H	16.10 typ.		0.634 typ.	
L	9.0	9.60	0.354	0.378
L1	0.80	1.20	0.031	0.047
L2	0.80 typ.	1.25	0.031 typ.	0.049
V1	+10°		+10	

3 Ordering information

Table 8: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
FERD30H100STS	FD30H100STS	TO-220AB	1.38 g	50	Tube
FERD30H100SH	FD30 H100S	IPAK	0.32 g	75	Tube
FERD30H100SB-TR	FD30 H100S	DPAK	0.35 g	2500	Tape and reel

4 Revision history

Table 9: Document revision history

Date	Revision	Changes
07-Apr-2016	1	Initial release.
14-Nov-2017	2	Updated cover page.

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